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	Date revised	2020-11-23	checked by	Jay
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Item (项目)	Standard (标准)
Rated Voltage (Maximum)额定电压	1A AC/DC
Rated Current (Maximum)额定电流	250V AC/DC
Operating temperature range工作温度范围	-40°C ~ +105°C From -40 to +105 degree centigrade
Storage Temperature Range储存温度范围	5°C ~ +30°C From 5 to +30 degree centigrade

5.0 TEST STANDARD (测试条件)

5.1 Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows (除另有说明外,用以进行测量和测试的标准环境条件范围如下)

Ambient temperature(环境温度): 5°C to 35°C

Normal humidity (正常湿度): 45% to 85%

Air pressure (气压): 86Kpa to 106Kpa

5.2 However if doubt arises on the decision based on the measured Values under the above-mentioned Conditions. The following conditions shall be employed:

(但是在对判定产生疑问时,按下述状态实施)

Temperature (温度): 20±2°C


Relative humidity (相对湿度): 65±5%

Air pressure (气压): 86Kpa to 106Kpa

6. PERFORMANCE AND TEST DESCRIPTION (性能和测试类型)

6.1 APPEARANCE (外观)

ITEM	DESCRIPTION(类型)	TEST CONDITION(测试条件)	REQUIREMENT(要求)
1	Examination of Product (产品检查)	Per EIA-364-18 Visual and functional inspection. (依照 EIA-364-18 外观和功能性检查)	Meet requirements of product drawing. No evidence of physical Damage. (符合图面要求,无物理损伤)

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6.2 ELECTRICAL (电气)

ITEM	DESCRIPTION(类型)	TEST CONDITION (测试条件)	REQUIREMENT(要求)
1	Low level contact resistance. (接触电阻)	Per EIA-364-23 Subject mated connector with a max. voltage of 20mV and current of 100mA. (依照EIA-364-23 在配对连接器上施加最大20mV电压和100mA电流)	Initial \leq 20M Ω Max. Final = 30m Ω Max.
2	Dielectric Withstanding Voltage(耐电压)	Per EIA-364-20 Subject mated connector with a. voltage of 300V AC for 1 minute between adjacent terminals. (依照EIA-364-20 在配对好的连接器的相邻两个端子上接通300V的交流电, 持续1分钟)	No Breakdown. leakage Current: 5mA Max. (无击穿, 漏电流: 5mA最大)
3	Insulation Resistance (绝缘电阻)	Per EIA-364-21 Subject mated connector with a. voltage of 500V DC between adjacent terminals. (依照 EIA-364-21, 在配对好的连接器的相邻两个端子上接通500V 的直流电)	1000M Ω Min.

6.3 MECHANICAL (机械)

ITEM	DESCRIPTION(类型)	TEST CONDITION (测试条件)	REQUIREMENT(要求)
1	Contact Retention Force (保持力)	Per EIA-364-37 The end of a post shall be pulled in a perpendicular to base housing at a constant speed of 25.4mm/minute. (依照 EIA-364-37, 垂直与基壳方向上以 25.4mm/minute 恒定的测试速度拉端子末端)	1.00N Min. per pin.
2	Durability (耐久)	Per EIA-364-09 Perform 100 cycle Mating/unmating at a rate of 25.4mm/minute. (依照 EIA-364-09以25.4mm/minute匀速速度循环插拔100次)	No evidence of physical damage 无物理损伤现象

6.4 ENVIRONMENTAL (环境)

ITEM	DESCRIPTION(类型)	TEST CONDITION(测试条件)	REQUIREMENT(要求)
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1	Thermal Shock (冷热冲击)	<p>Per EIA-364-32, Mated connectors: expose to 5cycles of: (依照EIA-364-32, 执行如下条件的5次循环)</p> <table border="1"> <thead> <tr> <th>Temperature°C 温度</th> <th>Duration(Minutes) 持续时间(分)</th> </tr> </thead> <tbody> <tr> <td>-40°C +0/-5</td> <td>30 Min.</td> </tr> <tr> <td>+25°C +10/-5</td> <td>5 Max.</td> </tr> <tr> <td>+105°C +3/-0</td> <td>30 Min.</td> </tr> <tr> <td>+25°C +10/-5</td> <td>5 Max.</td> </tr> </tbody> </table>	Temperature°C 温度	Duration(Minutes) 持续时间(分)	-40°C +0/-5	30 Min.	+25°C +10/-5	5 Max.	+105°C +3/-0	30 Min.	+25°C +10/-5	5 Max.	No evidence of physical damage 无物理损伤现象
Temperature°C 温度	Duration(Minutes) 持续时间(分)												
-40°C +0/-5	30 Min.												
+25°C +10/-5	5 Max.												
+105°C +3/-0	30 Min.												
+25°C +10/-5	5 Max.												
2	Temperature Life (高温寿命测试)	Per EIA-364-17 Test Condition: 105°C, 96hours. (依照EIA-364-17, 测试条件: 105°C, 96小时。)	No evidence of physical damage 无物理损伤现象										
3	Humidity Test (湿度测试)	Per EIA-364-31 Test Condition: 40±2°C, 90-95% RH, 96 hrs. (依照 EIA-364-31, 测试条件: 40±2°C, 90-95% RH, 96小时)	No evidence of physical damage 无物理损伤现象										
4	Salt Spray (盐雾)	<p>Per EIA-364-26 Test Condition: Temperature: 35±2°C; Atmosphere: 5% salt-solution. Duration: 16 hours exposure for gold area; 8 hours exposure for tin area. (依照 EIA-364-26 测试条件: 35±2°C, 锡区域: 8 小时; 金区域: 16 小时, 5% 盐溶液。)</p>	No evidence of physical damage 无物理损伤现象										
5	Solder ability Test (可焊性测试)	Per EIA-364-71 Test Temperature: 245±3°C, 3~5sec. (依照EIA-364-71 测试温度: 245±3°C, 3~5秒)	After exposure, the contact solder tails shall have a minimum of 95% solder coverage. (风干后, 端子焊锡覆盖率至少95%。)										
6	Resistance to Soldering Heat (焊接耐热性)	<p>Per EIA- 364- 56 Soldering iron method Solder Temp.: 380±10°C/3~5 seconds. Reflow(Only suitable for the materials with high temperature resistance.): Please see recommended profile. Pre Heat: 150°C~200°C/60 to 120 seconds Heat: 217 °C;60-150 seconds Peak Temp.: 260±5°C/5~15 seconds. (依照EIA-364-56, 手工焊接温度: 380 ±10°C/3~5秒, 回流焊(适用于耐高温材料): 预加热: 150°C~200°C / 60 -120 秒; 加热: 217 ° C;60-150 秒; 最高温度: 260±5°C /5~15 秒)</p>	No evidence of physical damage 无物理损伤现象										

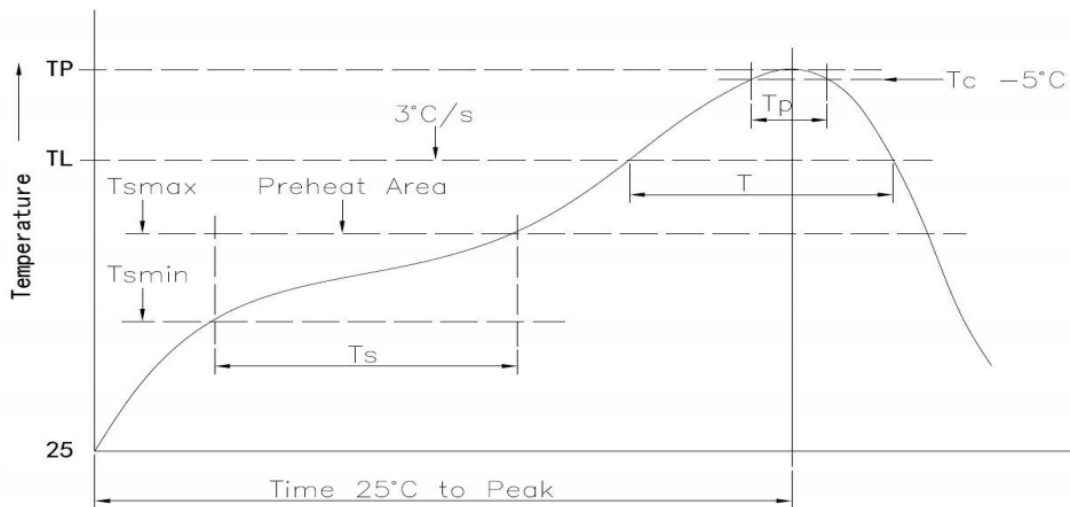


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7. INFRARED REFLOW CONDITION (LEAD-FREE) 红外回流焊条件（无铅）：



Profile Feature (特性)	Pb-Free Assembly (无铅组装)
Preheat & Soak (预热&浸泡) Temperature min (Ts min) (最低温度) Temperature max (Ts max) (最高温度) Time (Ts min to Ts max) (ts) (时间)	150°C~200°C/60 to 120 seconds
Average ramp-up rate (Ts max to Tp) (平均温升率)	3 °C/second max.
Liquidous temperature (TL) (液化温度) Time at liquidous (TL) (液化时间)	217 °C 60-150 seconds
Peak package body temperature (Tp)* (封装最高温度)	260±5°C/5~15 seconds
Time (tp)** within 5 °C of the specified classification temperature (Tc) (在指定等级温度5°C内的时间)	20~40seconds